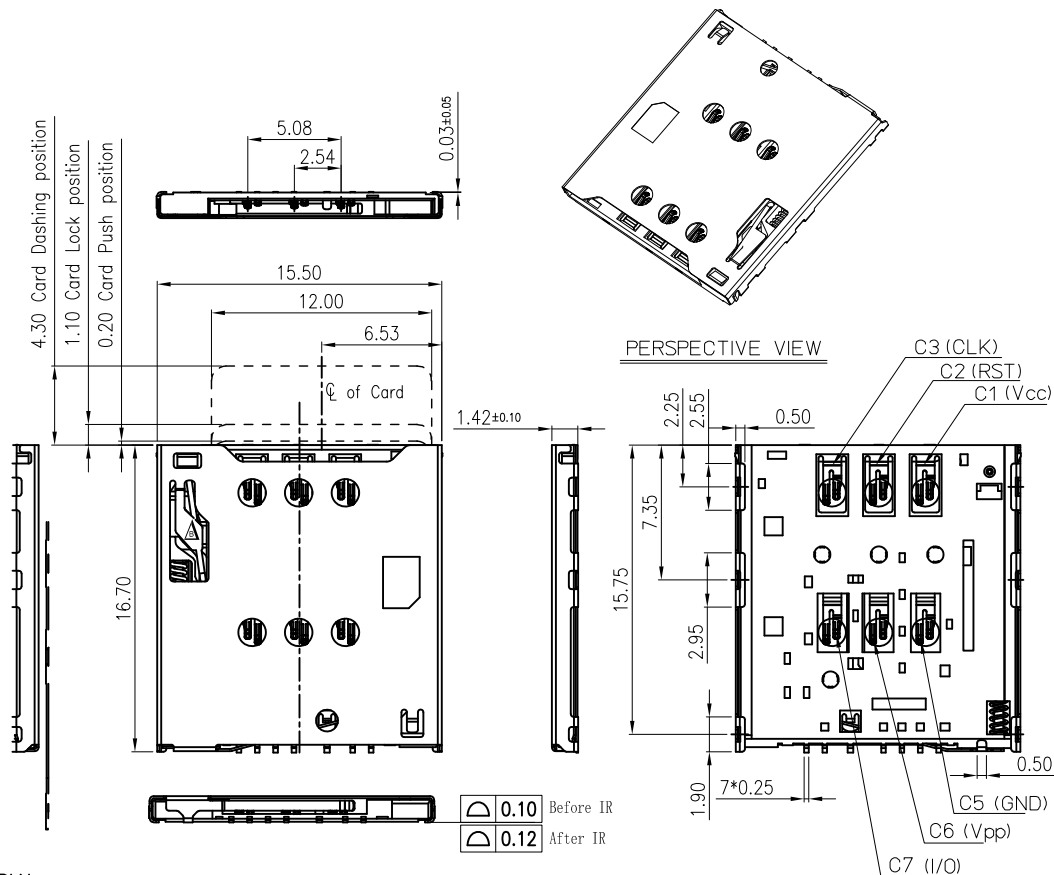


更改 REV	說明 MODIFICATION
A	EC06509
B	EC06824
C	EC07125



MATERIAL:

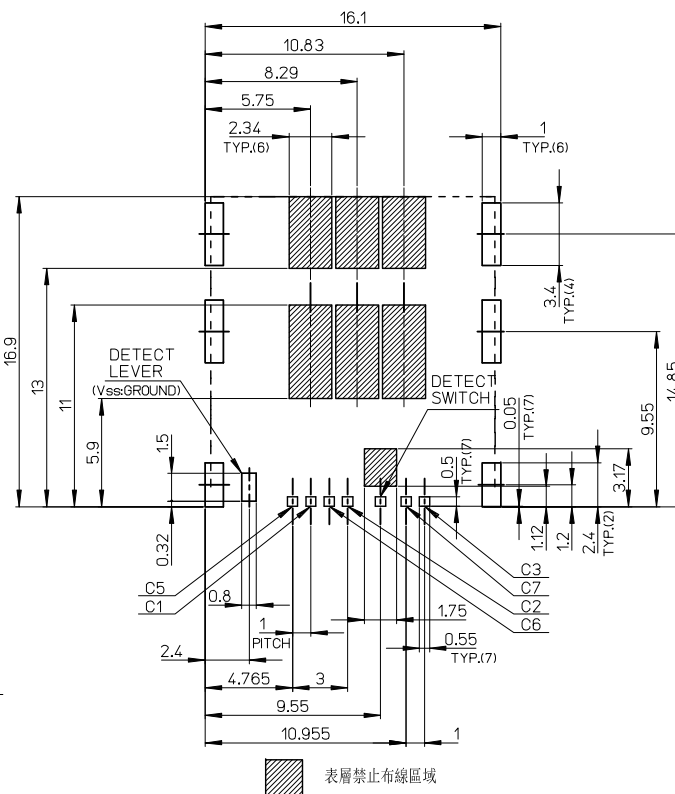
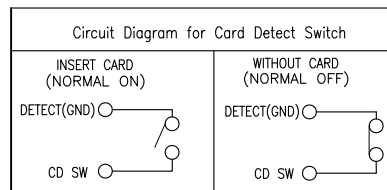
Insulator: High Temperature Thermoplastic, UL 94-0.
Contact: Copper Alloy.
SHELL: SUS.

PLATING:

Contact: Plated 50u" Ni Overall Contact Au 1u".
Shell: Plated 50u" Ni Overall Plated 1u" Au
Selective Contact Area.

Electrical:

Current Rating: 0.5A AC/DC max.
Voltage Rating: 125V AC/DC.
▲ DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE.
▲ Storage Temperature Range: -40°C~+85°C.
▲ Operation Temperature Range: -40°C~+85°C.
Ambient Humidity Range: 95% R.H. Max.
Contact Resistance: 100mΩ max.
Insulation Resistance: 1minute 500VDC.
High temperature resistant: 260°
Mating Cycles: 5000Min Insertions.



RECOMMENDED PCB PATTERN LAYOUT
(GENERAL TOLERANCE : ±0.05)



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X.± 0.50	X.± 5	名廠(TITLE) Micro sim push H1.42mm	
.X± 0.30	.X'± 2		
.XX± 0.20	.XX'± 1		
單位(UNIT)	料號(PART NO.)	圖號(DWG NO.)	張數(SHEET)
mm	7SIMC-F0-0041	7SIMC-F0-0041-C	1/1
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)	比例(SCALE)
			1:1
			更改(REV)
			C